



SOD995

leadless ultra small package; 2 terminals; body 1.0 x 0.6 x 0.27 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	DSN1006U-2
Package type industry code	DSN1006U-2
Package style descriptive code	USON (ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-12-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.55	-	0.6	0.65	mm
E	package width		0.95	-	1	1.05	mm
A	seated height		0.24	-	0.27	0.3	mm
e	nominal pitch		-	-	0.325	-	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline

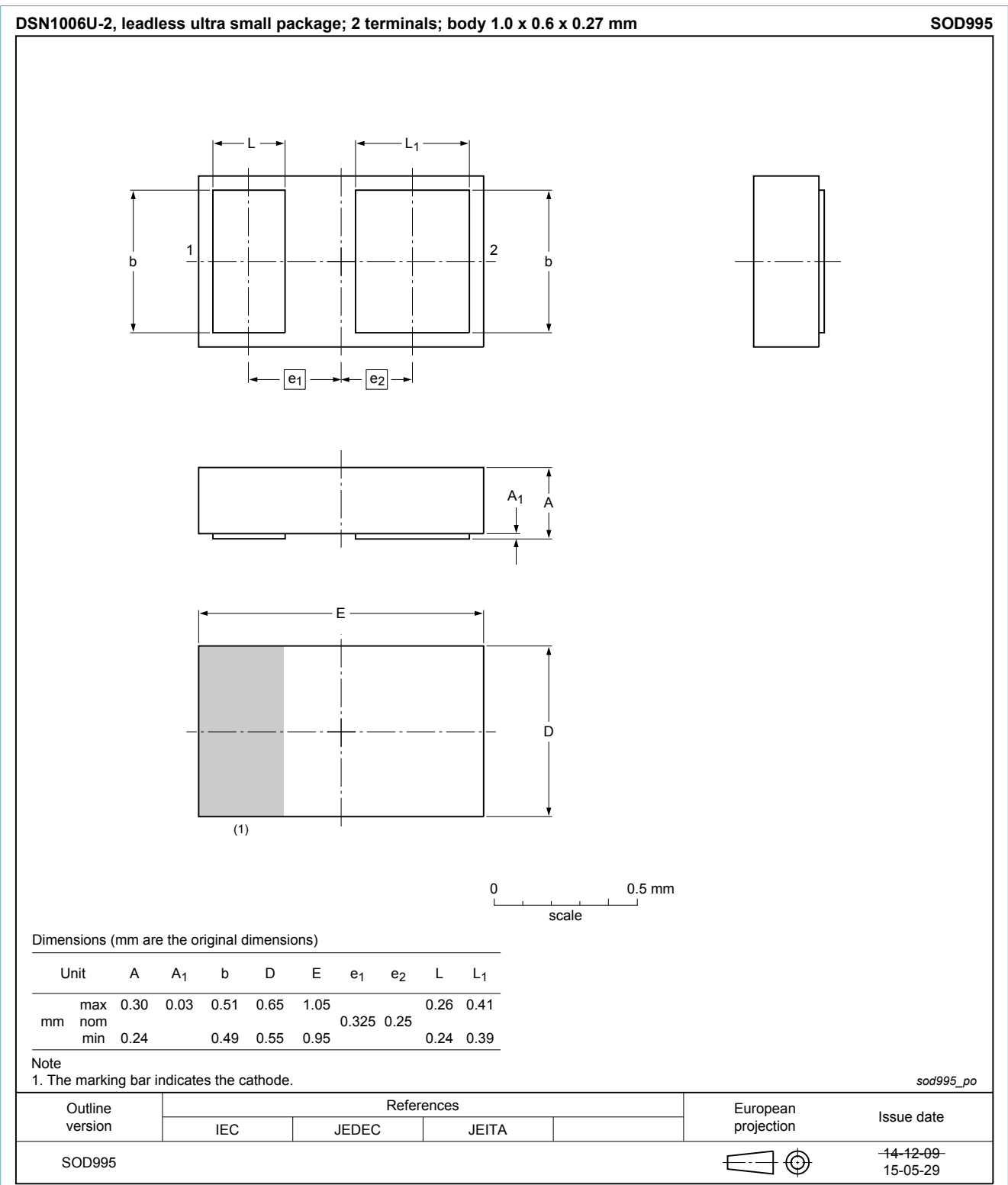


Fig. 1. Package outline DSN1006U-2 (SOD995)

leadless ultra small package; 2 terminals; body
1.0 x 0.6 x 0.27 mm

3. Soldering

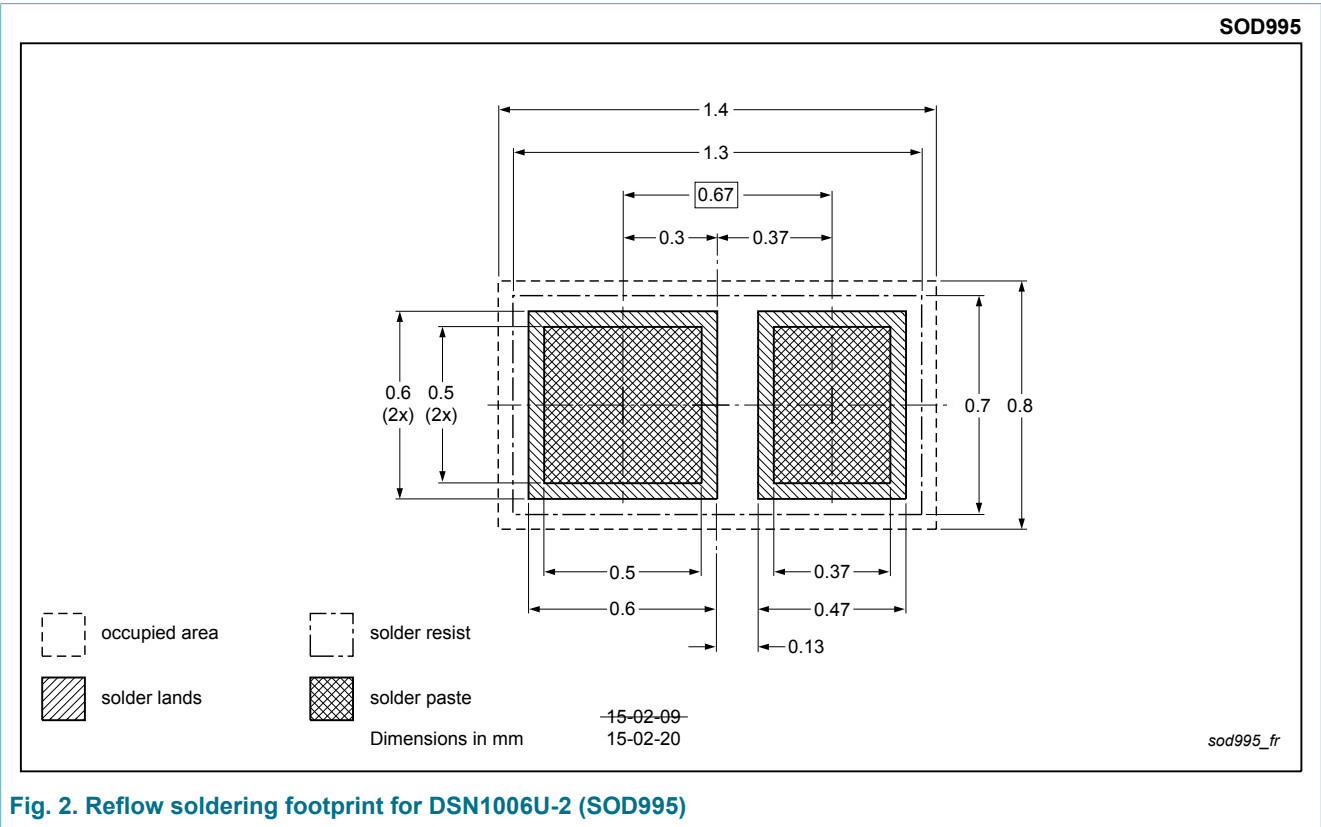


Fig. 2. Reflow soldering footprint for DSN1006U-2 (SOD995)

4. Legal information

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